

VC7002X

N-Channel Enhancement Mode Field Effect Transistor

Product Summary

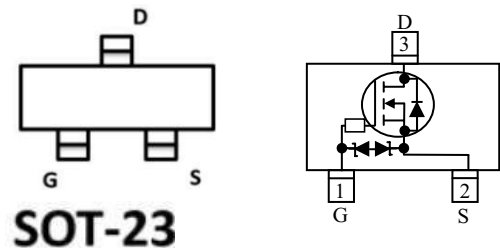
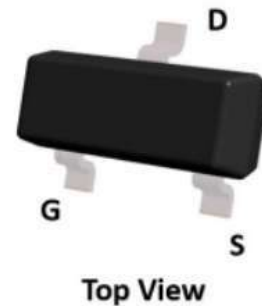
- $V_{DS} = 60V, I_D = 0.3A$
 $R_{DS(ON)} < 3\Omega @ V_{GS}=5V$
 $R_{DS(ON)} < 2\Omega @ V_{GS}=10V$

General Description

- Trench Power LV MOSFET technology
- High Power and current handling capability

Applications

- PWM application
- Load switch



■ ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ C$, unless otherwise specified.)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V _{DSS}	60	V
Drain-Gate Voltage (R _{GS} ≤1MΩ)		V _{DGR}	60	V
Gate Source Voltage	Continuous	V _{GSS}	±20	V
Drain Current	Continuous	I _D	300	mA
	Pulsed		900	
Power Dissipation		P _D	200	mW
Derated Above 25°C			1.6	mW/°C
Junction Temperature		T _J	+ 150	°C
Storage Temperature		T _{STG}	-55 ~ +150	°C

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.
 Absolute maximum ratings are stress ratings only and functional device operation is not implied.

■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	625	$^\circ C/W$
Junction to Case	θ_{JC}	215	$^\circ C/W$

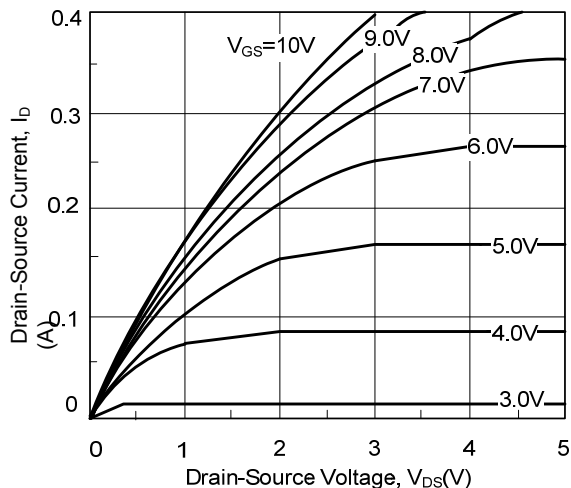
■ ELECTRICAL CHARACTERISTICS ($T_A=25^{\circ}\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =10μA	6			V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			1	μA
Gate-Source Leakage Current	I _{GSSF}	V _{GS} =20V, V _{DS} =0V			10	μA
	I _{GSSR}	V _{GS} =-20V, V _{DS} =0V			-10	μA
ON CHARACTERISTICS (Note)						
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} =V _{DS} , I _D =250μA	1.1	1.4	2.2	V
Static Drain-Source On-Resistance	R _{DS (ON)}	V _{GS} =10V, I _D =300mA		1.6	2.0	Ω
		V _{GS} =4.5V, I _D =200mA		2.4	3.0	Ω
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{ISS}	V _{DS} =25V, V _{GS} =0V, f=1.0MHz			50	pF
Output Capacitance	C _{OSS}				25	pF
Reverse Transfer Capacitance	C _{RSS}				5	pF
Turn-On Time	t _{ON}	V _{DD} =30V, R _L =150Ω, I _D =200mA,			20	nS
Turn-Off Time	t _{OFF}	V _{GS} =10V, R _G =25Ω			20	nS
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Maximum Continuous Drain-Source Diode Forward Current	I _S				300	mA
Maximum Pulsed Drain-Source Diode Forward Current	I _{SM}				0.95	A
Drain-Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =300mA (Note)		0.88	1.5	V

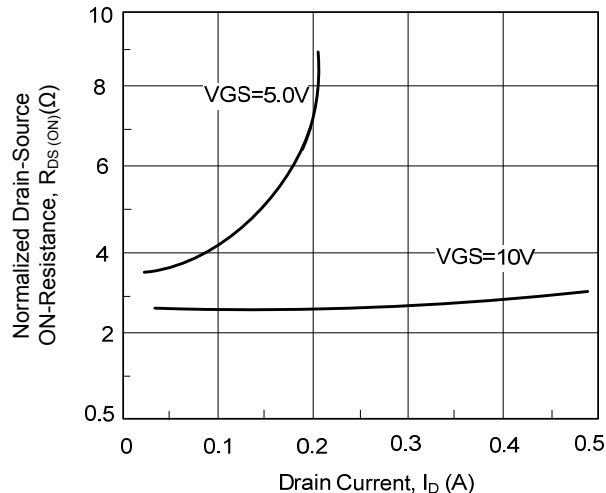
Note: Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2.0\%$

■ TYPICAL CHARACTERISTICS

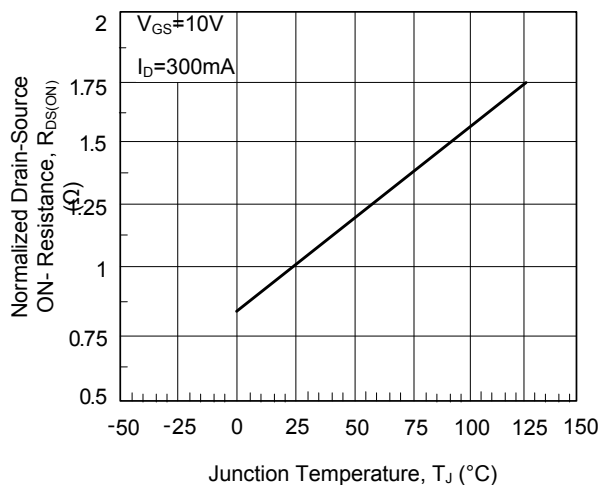
On-Resistance Characteristics



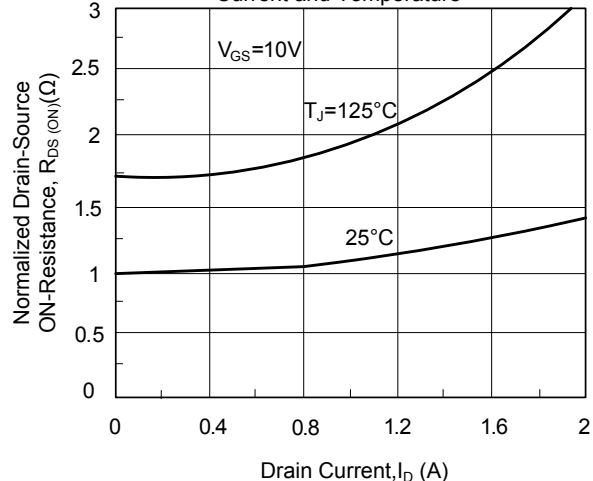
On-Resistance Variation with Gate Voltage and Drain Current



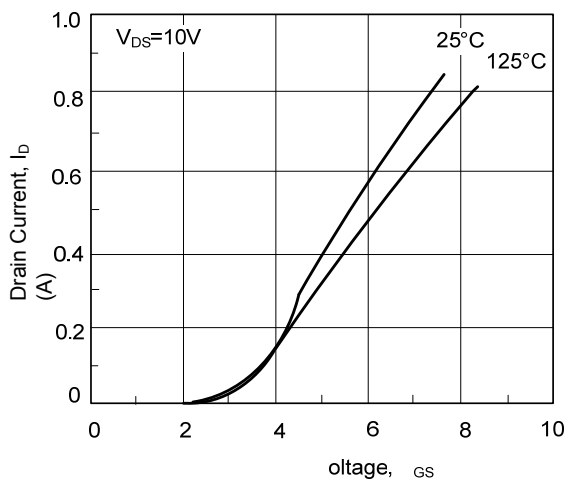
On-Resistance Variation with Temperature



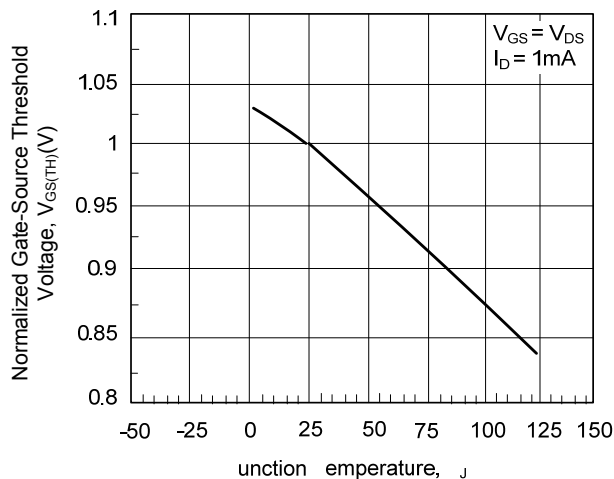
On-Resistance Variation with Drain Current and Temperature



Transfer Characteristics

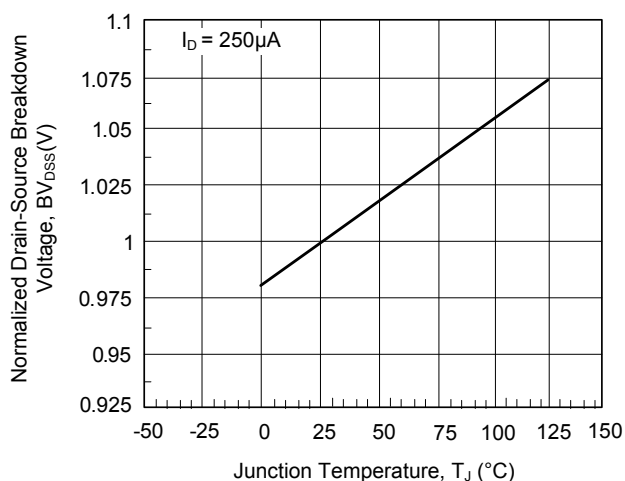


Gate Threshold Variation with Temperature

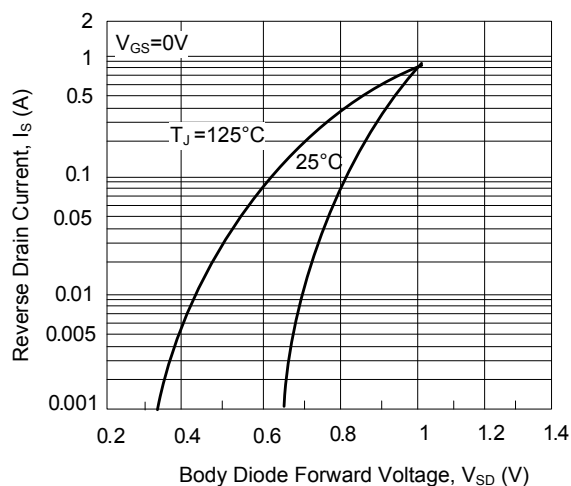


■ TYPICAL CHARACTERISTICS(Cont.)

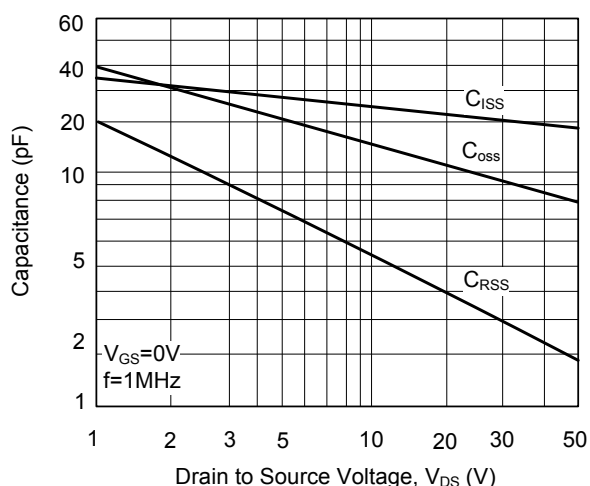
Breakdown Voltage Variation with Temperature



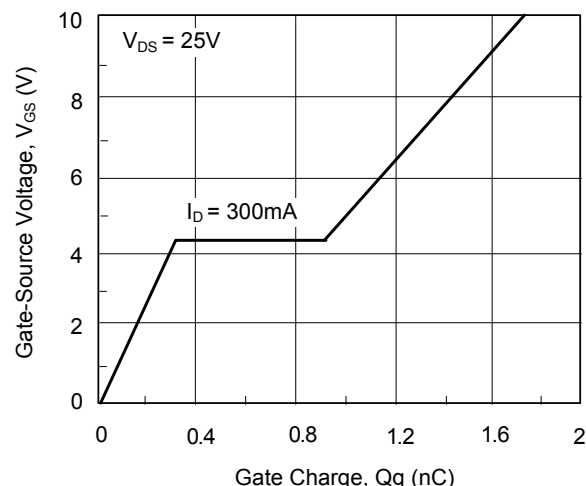
Body Diode Forward Voltage Variation with Temperature



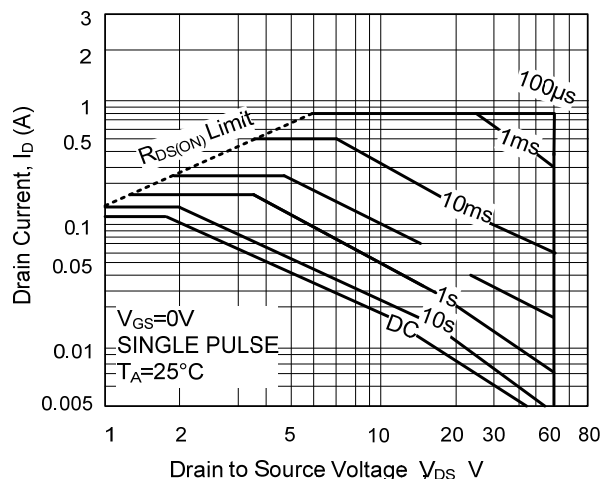
Capacitance Characteristics



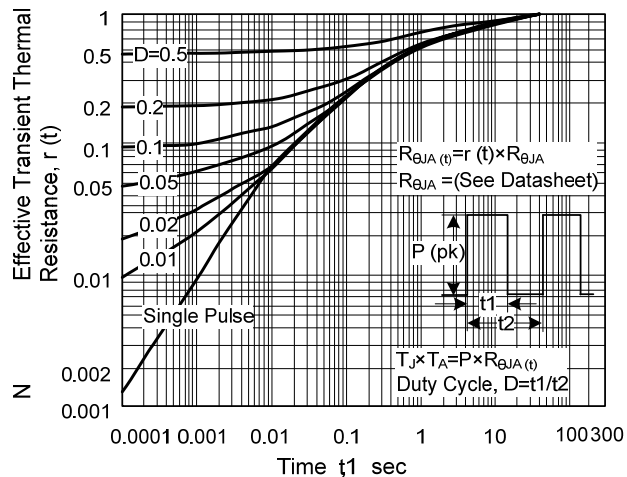
Gate Charge Characteristics



Maximum Safe Operating Area



Transient Thermal Response Curve



■ TEST CIRCUIT AND WAVEFORM

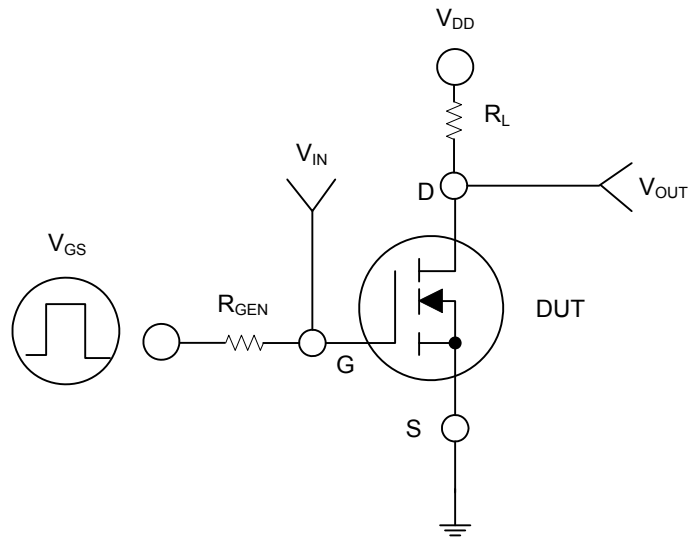


Fig. 1

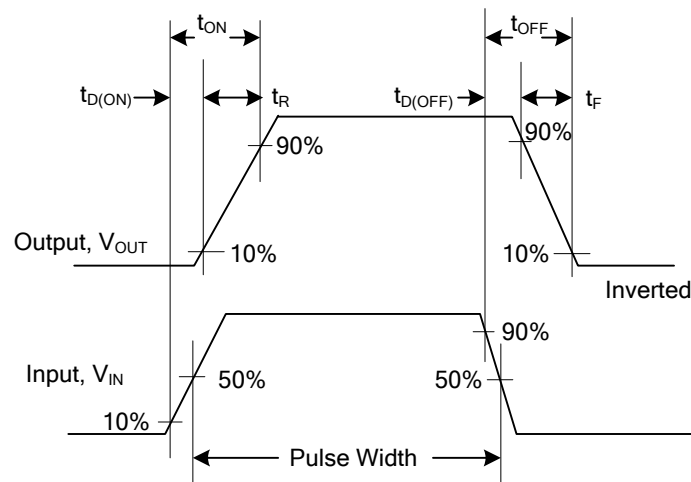
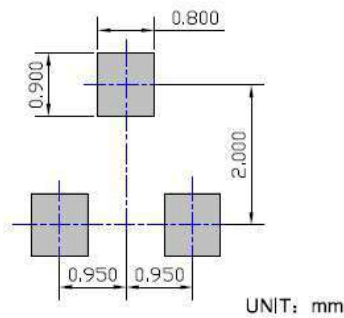
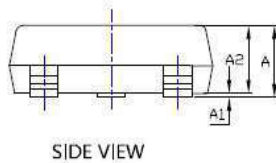
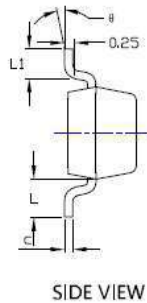
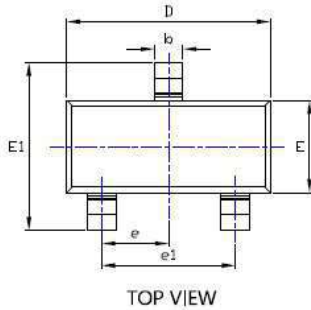


Fig. 2 Switching Waveforms

■ SOT-23 Package information



SUGGESTED SOLDER PAD LAYOUT

SYMBOL	DIMENSIONS					
	INCHES			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.035	---	0.045	0.900	---	1.150
A1	0.000	---	0.004	0.000	---	0.100
A2	0.035	0.038	0.041	0.900	0.975	1.050
b	0.012	0.016	0.020	0.300	0.400	0.500
c	0.004	---	0.008	0.100	---	0.200
D	0.110	0.114	0.118	2.800	2.900	3.000
E	0.047	0.051	0.055	1.200	1.300	1.400
E1	0.089	0.094	0.100	2.250	2.400	2.550
e	0.037 TYP			0.950 TYP		
e1	0.071	0.075	0.079	1.800	1.900	2.000
L	0.022 REF			0.550 REF		
L1	0.012	0.016	0.200	0.300	0.400	0.500
ø	0*	---	8*	0*	---	8*

NOTE:

1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
2. TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
3. THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

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